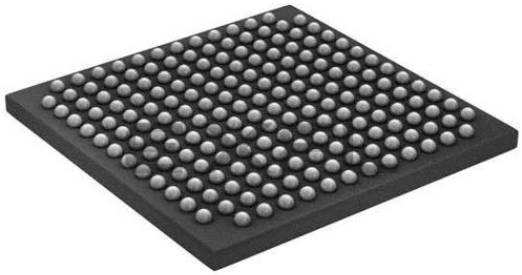

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CSIO, EBI/EMI, Ethernet, I²C, LINbus, SD, SPI, UART/USART, USB
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	152
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	192-LFBGA
Supplier Device Package	192-FBGA (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2c28j0agb1000a

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
59	49	41	L4	P43 SIN15_0 RTO13_0 (PPG12_0) TIOA3_0 INT04_0 MCSX4_0	G	K
60	50	42	M4	P44 SOT15_0 (SDA15_0) RTO14_0 (PPG14_0) TIOA4_0 MCSX3_0	G	I
61	51	43	N4	P45 SCK15_0 (SCL15_0) RTO15_0 (PPG14_0) TIOA5_0 MCSX2_0	G	I
62	52	44	P2	C	-	-
63	53	45	P3	VSS	-	-
64	54	46	P4	VCC	-	-
65	-	-	-	P4A SIN12_1 AIN0_1 INT04_2	E	K
66	-	-	-	P4B SOT12_1 (SDA12_1) BIN0_1	E	I
67	-	-	-	P4C SCK12_1 (SCL12_1) ZIN0_1	E	I
68	-	-	-	P4D SCS72_1 INT05_2	E	K
69	-	-	-	P4E SCS73_1	E	I
70	55	47	L5	P7D SCK1_1 (SCL1_1) DTTI1X_0 INT05_0 WKUP2 MCSX1_0	L	Q
71	56	48	M5	P7E ADTG_7 FRCK1_0 MCSX0_0	L	I
72	57	49	N5	INITX	B	C
73	58	50	P5	P46 X0A	P	S

Pin Number				Pin Name	I/O Circuit Type	Pin State Type
LQQ216	LQP176	LQS144	LBE192			
115	95	79	K13	P11 AN01 SOT10_0 (SDA10_0) TIOB0_2 BIN0_2	F	L
116	96	80	K12	P12 AN02 SCK10_0 (SCL10_0) TIOA1_2 ZIN0_2	F	L
117	97	81	K14	P13 AN03 SIN6_1 INT25_1	F	M
118	98	82	K11	P14 AN04 SOT6_1 (SDA6_1)	F	L
119	-	-	-	PB8 ADTG_6 SCS63_1 INT08_2 TRACED8	E	O
120	-	-	-	PB9 SIN9_1 AIN2_2 INT09_2 TRACED9	E	O
121	-	-	-	PBA SOT9_1 (SDA9_1) BIN2_2 TRACED10	E	N
122	-	-	-	PBB SCK9_1 (SCL9_1) ZIN2_2 TRACED11	E	N
123	99	83	J13	P15 AN05 SIN11_0 TIOB1_2 AIN1_2 INT09_0	F	M
124	100	84	J12	P16 AN06 SOT11_0 (SDA11_0) TIOA2_2 BIN1_2	F	L

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
External bus	MCLKOUT_0	External bus interface external clock output pin	32	23	20	G5
	MNALE_0	External bus interface ALE signal to control NAND flash output pin	47	37	32	K2
	MNCLE_0	External bus interface CLE signal to control NAND flash output pin	48	38	33	K3
	MNREX_0	External bus interface read enable signal to control NAND flash	50	40	35	L1
	MNWEX_0	External bus interface write enable signal to control NAND flash	49	39	34	K4
	MOEX_0	External bus interface read enable signal for SRAM	209	169	137	C5
	MWEX_0	External bus interface write enable signal for SRAM	210	170	138	B4
	MSDCLK_0	SDRAM interface SDRAM clock output pin	90	75	-	L9
	MSDCKE_0	SDRAM interface SDRAM clock enable pin	89	74	-	M9
	MRASX_0	SDRAM interface SDRAM column active strobe pin	85	70	-	N8
	MCASX_0	SDRAM interface SDRAM row active strobe pin	86	71	-	M8
	MSDWEX_0	SDRAM interface SDRAM write enable pin	87	72	-	N9
External interrupt	INT00_0	External interrupt request 00 input pin	2	2	2	B2
	INT00_1		38	28	23	H3
	INT00_2		19	-	-	-
	INT01_0	External interrupt request 01 input pin	7	7	7	D1
	INT01_1		41	31	26	H6
	INT01_2		51	41	-	L2
	INT02_0	External interrupt request 02 input pin	14	13	10	E5
	INT02_1		42	32	27	J5
	INT02_2		26	-	-	-
	INT03_0	External interrupt request 03 input pin	17	16	13	F3
	INT03_1		43	33	28	J4
	INT03_2		34	24	-	G6
	INT04_0	External interrupt request 04 input pin	59	49	41	L4
	INT04_1		100	83	67	M11
	INT04_2		65	-	-	-
	INT05_0	External interrupt request 05 input pin	70	55	47	L5
	INT05_1		86	71	-	M8
	INT05_2		68	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
GPIO	P30	General-purpose I/O port 3	34	24	-	G6
	P31		35	25	-	H4
	P32		36	26	21	H2
	P33		37	27	22	J1
	P34		38	28	23	H3
	P35		41	31	26	H6
	P36		42	32	27	J5
	P37		43	33	28	J4
	P38		44	34	29	J3
	P39		45	35	30	J2
	P3A		46	36	31	K1
	P3B		47	37	32	K2
	P3C		48	38	33	K3
	P3D		49	39	34	K4
	P3E		50	40	35	L1
	P40	General-purpose I/O port 4	56	46	38	N2
	P41		57	47	39	N3
	P42		58	48	40	M3
	P43		59	49	41	L4
	P44		60	50	42	M4
	P45		61	51	43	N4
	P46		73	58	50	P5
	P47		74	59	51	P6
	P48		76	61	53	N6
	P49		77	62	54	M6
	P4A		65	-	-	-
	P4B		66	-	-	-
	P4C		67	-	-	-
	P4D		68	-	-	-
	P4E		69	-	-	-

6. Handling Precautions

Every semiconductor device has a characteristic, inherent rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

6.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

Processing and Protection of Pins

These precautions must be followed when handling the pins that connect semiconductor devices to power supply and I/O functions.

1. Preventing Over-Voltage and Over-Current Conditions

   Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.
2. Protection of Output Pins

   Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions, if present for extended periods of time, can damage the device; therefore, avoid this type of connection.
3. Handling of Unused Input Pins

   Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power-supply pin or ground pin.

List of Pin Behavior by Mode State

Pin Status Type	Function Group	Power-On Reset or Low-Voltage Detection State	INITX Input State	Device Internal Reset State	Run mode or Sleep mode State	Timer mode, RTC mode, or Stop mode State		Deep Standby RTC mode or Deep Standby Stop mode State		Return From Deep Standby mode State
		Power Supply Unstable	Power Supply Stable		Power Supply Stable	Power Supply Stable		Power Supply Stable		Power Supply Stable
		-	INITX=0	INITX=1	INITX=1	INITX=1		INITX=1		INITX=1
		-	-	-	-	SPL=0	SPL=1	SPL=0	SPL=1	-
A	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	Main crystal oscillator input pin/ external main clock input selected	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input Enabled
B	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	GPIO selected, internal input fixed at 0	Hi-Z/internal input fixed at 0	GPIO selected
	External main clock input selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/internal input fixed at 0	Maintain previous state	Hi-Z/internal input fixed at 0	Maintain previous State
	Main crystal oscillator output pin	Hi-Z/ internal input fixed at 0/ or input enable	Hi-Z/ internal input fixed at 0	Hi-Z/ internal input fixed at 0	Maintain previous state while oscillator active/ When oscillation stops*1, it will be Hi-Z/ Internal input fixed at 0					
C	INITX input pin	Pull-up/ input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled	Pull-up/ Input enabled
D	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
E	Mode input pin	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled
	GPIO selected	Setting disabled	Setting disabled	Setting disabled	Maintain previous state	Maintain previous state	Hi-Z/ input enabled	GPIO selected	Hi-Z/ input enabled	GPIO selected

Ethernet-MAC Pins

Pin Name	Ethernet-MAC Function	Except For Ethernet-MAC Function	Power Supply Type
P6E/ADTG_5/SCK4_1/IC23_1/INT29_0/E_PPS	E_PPS *	P6E/ADTG_5/SCK4_1/IC23_1/INT29_0	V_{CC}
PC0/E_RXER	E_RXER	PC0	$ETHV_{CC}$
PC1/TIOB6_0/E_RX03	E_RX03	PC1/TIOB6_0	
PC2/TIOA6_0/E_RX02	E_RX02	PC2/TIOA6_0	
PC3/TIOB7_0/E_RX01	E_RX01	PC3/TIOB7_0	
PC4/TIOA7_0/E_RX00	E_RX00	PC4/TIOA7_0	
PC5/TIOB14_0/E_RXDV	E_RXDV	PC5/TIOB14_0	
PC6/TIOA14_0/E_MDIO	E_MDIO	PC6/TIOA14_0	
PC7/INT13_0/E_MDC/CROUT_1	E_MDC	PC7/INT13_0/CROUT_1	
PC8/E_RXCK_REFCK	E_RXCK_REFCK	PC8	
PC9/TIOB15_0/E_COL	E_COL	PC9/TIOB15_0	
PCA/TIOA15_0/E_CRS	E_CRS	PCA/TIOA15_0	
PCB/INT28_0/E_COUT	E_COUT	PCB/INT28_0	
PCC/E_TCK	E_TCK	PCC	
PCD/SOT4_1/INT14_0/E_TXER	E_TXER	PCD/SOT4_1/INT14_0	
PCE/SIN4_1/INT15_0/E_TX03	E_TX03	PCE/SIN4_1/INT15_0	
PCF/RTS4_1/INT12_0/E_TX02	E_TX02	PCF/RTS4_1/INT12_0	
PD0/INT30_1/E_TX01	E_TX01	PD0/INT30_1	
PD1/INT31_1/E_TX00	E_TX00	PD1/INT31_1	
PD2/CTS4_1/FRCK2_1/E_TXEN	E_TXEN	PD2/CTS4_1/FRCK2_1	

*: It is used to confirm the PTP counter cycle in Ethernet-MAC by waveforms.

Calculation Method of Power Dissipation (Pd)

The power dissipation is shown in the following formula.

$$Pd = V_{CC} \times I_{CC} + \Sigma (I_{OL} \times V_{OL}) + \Sigma ((V_{CC}-V_{OH}) \times (-I_{OH}))$$

I_{OL}: L level output current
I_{OH}: H level output current
V_{OL}: L level output voltage
V_{OH}: H level output voltage

I_{CC} is the current drawn by the device.
It can be analyzed as follows.

$$I_{CC} = I_{CC}(INT) + \Sigma I_{CC}(IO)$$

I_{CC} (INT): Current drawn by internal logic and memory, etc. through the regulator

ΣI_{CC} (IO): Sum of current (I/O switching current) drawn by the output pin

For I_{CC} (INT), it can be anticipated by (1) Current Rating in 12.3. DC Characteristics (This rating value does not include I_{CC} (IO) for a value at pin fixed).
For I_{CC} (IO), it depends on system used by customers.
The calculation formula is shown below.

$$I_{CC}(IO) = (C_{INT} + C_{EXT}) \times V_{CC} \times f_{SW}$$

C_{INT}: Pin internal load capacitance
C_{EXT}: External load capacitance of output pin
f_{SW}: Pin switching frequency

Parameter	Symbol	Conditions	Capacitance Value
Pin internal load capacitance	C_{INT}	4 mA type	1.93 pF
		8 mA type	3.45 pF
		12 mA type	3.42 pF

Calculate I_{CC} (Max) as follows when the power dissipation can be evaluated by yourself:

Measure current value I_{CC} (Typ) at normal temperature (+25°C).

Add maximum leakage current value I_{CC} (leak_max) at operating on a value in (1).

$$I_{CC}(Max) = I_{CC}(Typ) + I_{CC}(leak\_max)$$

Parameter	Symbol	Conditions	Current Value
Maximum leakage current at operating	I_{CC} (leak_max)	T_J = +125°C	79.2 mA
		T_J = +105°C	39.4 mA
		T_J = +85°C	26.5 mA

Table 12-5 Typical and Maximum Current Consumption in Sleep Operation (PLL), when PCLK0 = PCLK1 = PCLK2 = HCLK/2

Parameter	Symbol	Pin Name	Conditions	Frequency*4	Value		Unit	Remarks
					Typ*1	Max*2		
Power supply current	I_{CCS}	VCC	Sleep operation*5 (PLL)	200 MHz	88	188	mA	*3 When all peripheral clocks are on
				192 MHz	85	184	mA	
				180 MHz	80	178	mA	
				160 MHz	72	164	mA	
				144 MHz	65	156	mA	
				120 MHz	55	144	mA	
				100 MHz	47	134	mA	
				80 MHz	38	124	mA	
				60 MHz	30	114	mA	
				40 MHz	21	104	mA	
				20 MHz	12	93	mA	
				8 MHz	7.4	87.2	mA	
				4 MHz	5.8	85.2	mA	
				200 MHz	44	134	mA	*3 When all peripheral clocks are off
				192 MHz	42	132	mA	
				180 MHz	40	129	mA	
				160 MHz	36	123	mA	
				144 MHz	33	119	mA	
				120 MHz	28	113	mA	
				100 MHz	24	108	mA	
				80 MHz	20	103	mA	
				60 MHz	16	98	mA	
				40 MHz	12	93	mA	
				20 MHz	7.6	87.6	mA	
				8 MHz	5.2	84.7	mA	
				4 MHz	4.4	83.7	mA	

*1: T_A = +25°C, V_{CC} = 3.3 V

*2: T_J = +125°C, V_{CC} = 5.5 V

*3: When all ports are fixed

*4: Frequency is a value of HCLK when PCLK0 = PCLK1 = PCLK2 = HCLK/2

*5: When using the crystal oscillator of 4 MHz (including the current consumption of the oscillation circuit)

Table 12-6 Typical and Maximum Current Consumption in Sleep Operation (PLL), when PCLK0 = PCLK1 = PCLK2 = HCLK

Parameter	Symbol	Pin Name	Conditions	Frequency*4	Value		Unit	Remarks
					Typ*1	Max*2		
Power supply current	I_{CCS}	VCC	Sleep operation*5 (PLL)	72 MHz	45	130	mA	*3 When all peripheral clocks are on
				60 MHz	38	122	mA	
				48 MHz	31	114	mA	
				36 MHz	24	106	mA	
				24 MHz	18	99	mA	
				12 MHz	11	91	mA	
				8 MHz	8.6	88.3	mA	
				4 MHz	6.3	85.7	mA	
				72 MHz	20	103	mA	*3 When all peripheral clocks are off
				60 MHz	18	99	mA	
				48 MHz	15	96	mA	
				36 MHz	12	93	mA	
				24 MHz	9.1	89.3	mA	
				12 MHz	6.5	86.1	mA	
				8 MHz	5.5	84.9	mA	
				4 MHz	4.6	83.8	mA	

*1: T_A = +25°C, V_{CC} = 3.3 V

*2: T_J = +125°C, V_{CC} = 5.5 V

*3: When all ports are fixed

*4: Frequency is a value of HCLK when PCLK0 = PCLK1 = PCLK2 = HCLK

*5: When using the crystal oscillator of 4 MHz (including the current consumption of the oscillation circuit)

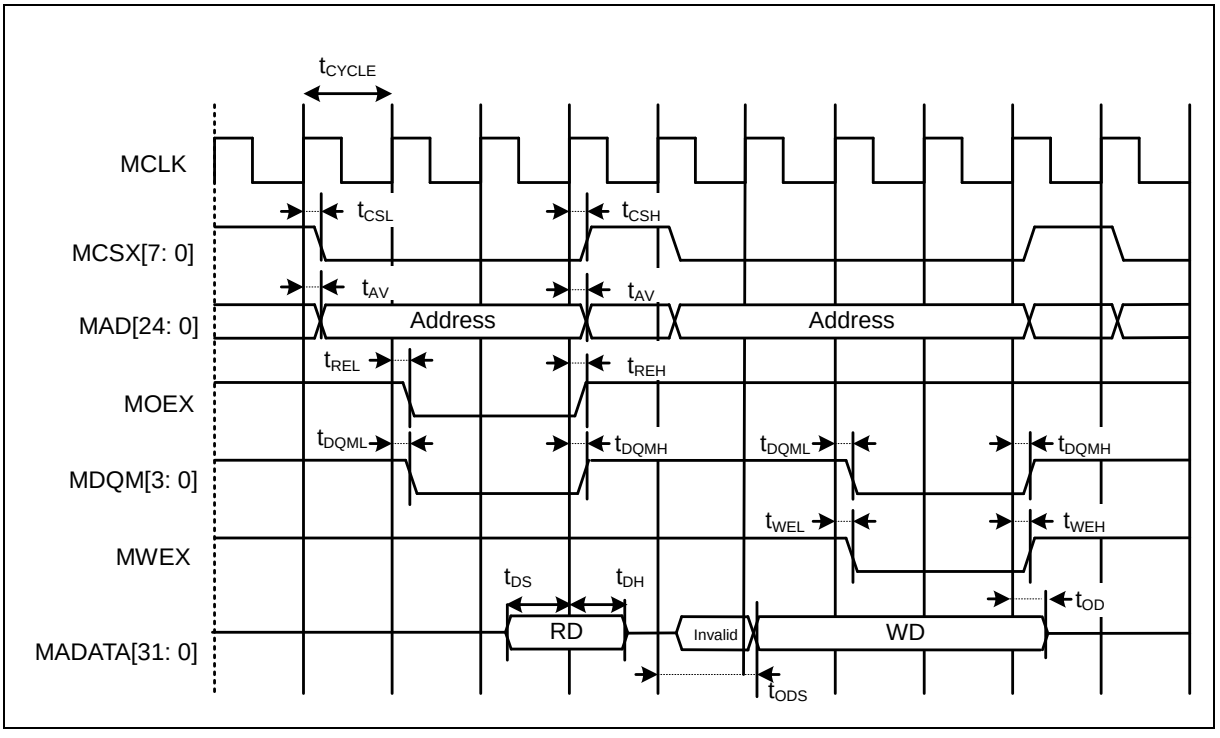
Separate Bus Access Synchronous SRAM Mode

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Address delay time	t_{AV}	MCLK, MAD[24: 0]	-	1	9	ns	
MCSX delay time	t_{CSL}	MCLK, MCSX[7: 0]	-	1	9	ns	
	t_{CSH}		-	1	9	ns	
MOEX delay time	t_{REL}	MCLK, MOEX	-	1	9	ns	
	t_{REH}		-	1	9	ns	
Data set up →MCLK ↑ time	t_{DS}	MCLK, MADATA[31: 0]	-	19	-	ns	
MCLK ↑ → Data hold time	t_{DH}	MCLK, MADATA[31: 0]	-	0	-	ns	
MWEX delay time	t_{WEL}	MCLK, MWEX	-	1	9	ns	
	t_{WEH}		-	1	9	ns	
MDQM[1: 0] delay time	t_{DQML}	MCLK, MDQM[3: 0]	-	1	9	ns	
	t_{DQMH}		-	1	9	ns	
MCLK ↑ → Data output time	t_{ODS}	MCLK, MADATA[31: 0]	-	MCLK+1	MCLK+18	ns	
MCLK ↑ → Data hold time	t_{OD}	MCLK, MADATA[31: 0]	-	1	18	ns	

Note:

- *When the external load capacitance C_L = 30 pF*



When Using Synchronous Serial Chip Select (SCINV = 1, CSLVL = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Units
			Min	Max	Min	Max	
SCS ↑ →SCK ↑ setup time	t_{CSSI}	Internal shift clock operation	(*1)-50	(*1)+0	(*1)-50	(*1)+0	ns
SCK ↓ →SCS ↓ hold time	t_{CSHI}		(*2)+0	(*2)+50	(*2)+0	(*2)+50	ns
SCS deselect time	t_{CSDI}		(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	(*3)-50 +5t_{CYCP}	(*3)+50 +5t_{CYCP}	ns
SCS ↑ →SCK ↑ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCK ↓ →SCS ↓ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+30	-	3t_{CYCP}+30	-	ns
SCS ↑ →SOT delay time	t_{DSE}		-	40	-	40	ns
SCS ↓ →SOT delay time	t_{DEE}		0	-	0	-	ns

(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]
(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]
(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*

When Using High-Speed Synchronous Serial Chip Select (SCINV = 1, CSLVL = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↓ setup time	t_{CSSI}	Internal shift clock operation	(*1)-20	(*1)+0	(*1)-20	(*1)+0	ns
SCK↑→SCS↓ hold time	t_{CSHI}		(*2)+0	(*2)+20	(*2)+0	(*2)+20	ns
SCS deselect time	t_{CSDI}		(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	(*3)-20 +5t_{CYCP}	(*3)+20 +5t_{CYCP}	ns
SCS↑→SCK↑ setup time	t_{CSSE}	External shift clock operation	3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCK↓→SCS↓ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		3t_{CYCP}+15	-	3t_{CYCP}+15	-	ns
SCS↑→SOT delay time	t_{DSE}		-	40	-	40	ns
SCS↓→SOT delay time	t_{DEE}		0	-	0	-	ns

(*1): CSSU bit value×serial chip select timing operating clock cycle [ns]

(*2): CSHD bit value×serial chip select timing operating clock cycle [ns]

(*3): CSDS bit value×serial chip select timing operating clock cycle [ns]

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *For more information about CSSU, CSHD, CSDS, and the serial chip select timing operating clock, see FM4 Family Peripheral Manual Main Part (002-04856).*
- *When the external load capacitance C_L = 30 pF.*

Fast Mode Plus (Fm+)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Conditions	Fast Mode Plus (Fm+)*6		Unit	Remarks
			Min	Max		
SCL clock frequency	f_{SCL}	C_L = 30 pF, R = (V_p/I_{OL})*1	0	1000	kHz	
(Repeated) Start condition hold time SDA ↓ → SCL ↓	t_{HDSTA}		0.26	-	µs	
SCL clock L width	t_{LOW}		0.5	-	µs	
SCL clock H width	t_{HIGH}		0.26	-	µs	
SCL clock frequency	t_{SUSTA}		0.26	-	µs	
(Repeated) Start condition hold time SDA ↓ → SCL ↓	t_{HDDAT}		0	0.45*2, *3	µs	
Data setup time SDA ↓ ↑ → SCL ↑	t_{SUDAT}		50	-	ns	
Stop condition setup time SCL ↑ → SDA ↑	t_{SUSTO}		0.26	-	µs	
Bus free time between Stop condition and Start condition	t_{BUF}		0.5	-	µs	
Noise filter	t_{SP}	60 MHz ≤ t_{CYCP} < 80 MHz	6 t_{CYCP}*4	-	ns	*5
		80 MHz ≤ t_{CYCP} ≤ 100 MHz	8 t_{CYCP}*4	-	ns	

*1: R and C_L represent the pull-up resistance and load capacitance of the SCL and SDA lines, respectively. V_p indicates the power supply voltage of the pull-up resistance and I_{OL} indicates V_{OL} guaranteed current.

*2: The maximum t_{HDDT} must not extend beyond the low period (t_{LOW}) of the device's SCL signal.

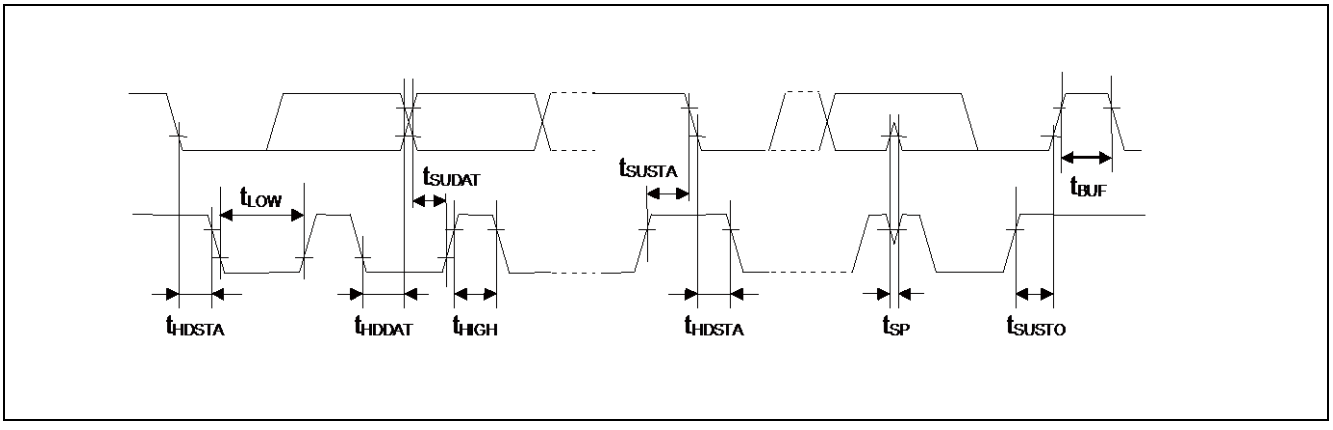
*3: The Fast mode I^2C bus device can be used on a Standard-mode I^2C bus system as long as the device satisfies the requirement of "t_{SUDAT} ≥ 250 ns."

*4: t_{CYCP} is the APB bus clock cycle time. For more information about the APB bus number to which the I^2C is connected, see "8.Block Diagram" in this data sheet.

To use fast mode plus (Fm+), set the peripheral bus clock at 64 MHz or more.

*5: The noise filter time can be changed by register settings. Change the number of the noise filter steps according to the APB bus clock frequency.

*6: When using fast mode plus (Fm+), set the I/O pin to the mode corresponding to I^2C Fm+ in the EPFR register. See Chapter 12: I/O Port in FM4 Family Peripheral Manual Main Part (002-04856) for the details.



High-Speed Mode

■Clock CLK (All values are referred to V_{IH} and V_{IL})

(V_{CC} = 2.7V to 3.6V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Remarks
				Min	Max	
Clock frequency Data Transfer Mode	f_{PP}	S_CLK	C_{CARD} ≤ 10 pF (1 card)	0	50	MHz
Clock low time	t_{WL}	S_CLK		7	-	ns
Clock high time	t_{WH}	S_CLK		7	-	ns
Clock rise time	t_{TLH}	S_CLK		-	3	ns
Clock fall time	t_{THL}	S_CLK		-	3	ns

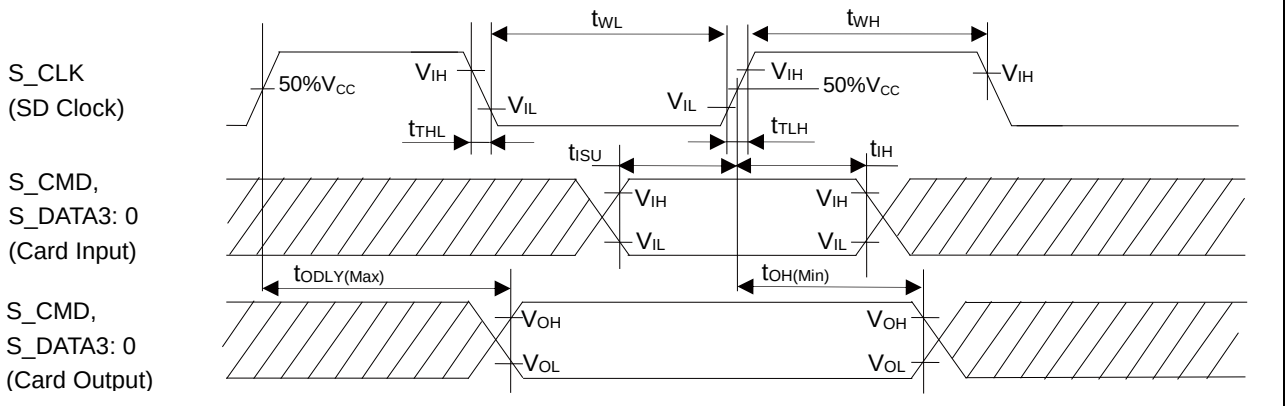
■Card Inputs CMD, DAT (referenced to Clock CLK)

Parameter	Symbol	Pin Name	Conditions	Value		Remarks
				Min	Max	
Input set-up time	t_{ISU}	S_CMD, S_DATA3: 0	C_{CARD} ≤ 10 pF (1 card)	6	-	ns
Input hold time	t_{IH}	S_CMD, S_DATA3: 0		2	-	ns

■Card Outputs CMD, DAT (referenced to Clock CLK)

Parameter	Symbol	Pin Name	Conditions	Value		Remarks
				Min	Max	
Output delay time during data transfer mode	t_{ODLY}	S_CMD, S_DATA3: 0	C_L ≤ 40 pF (1 card)	0	14	ns
Output hold time	t_{OH}	S_CMD, S_DATA3: 0	C_L ≥ 15 pF (1 card)	2.5	-	ns
Total system capacitance for each line*	C_L	-	1 card	-	40	pF

*: In order to satisfy severe timing, host shall drive only one card.



High-Speed Mode

Notes:

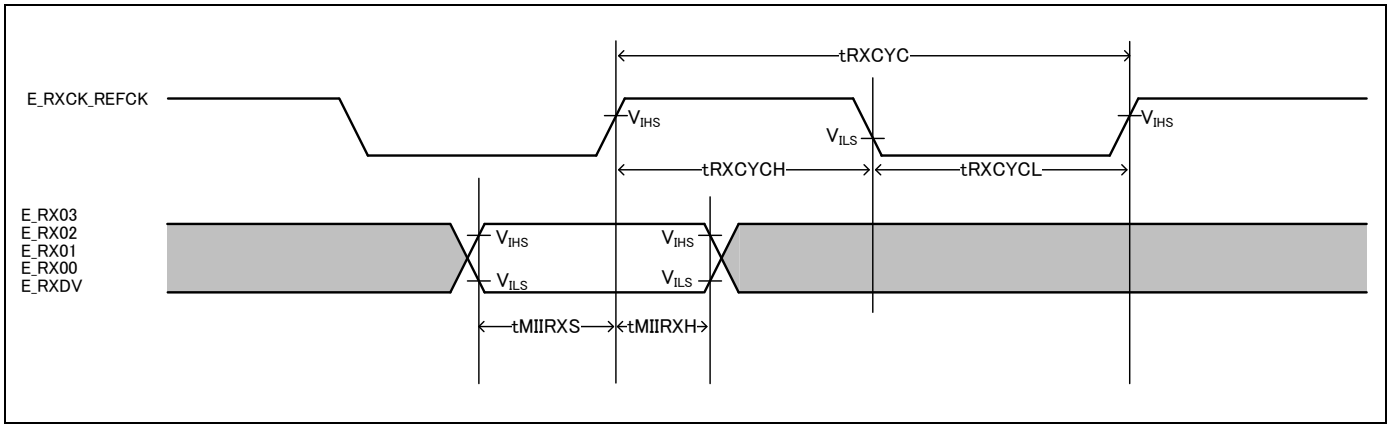
- *The Card Input corresponds to the Host Output and the Card Output corresponds to the Host Input because this model is the Host.*
- *For more information about clock frequency (f_{PP}), see Chapter 15: SD card Interface in FM4 Family Peripheral Manual Main Part (002-04856).*

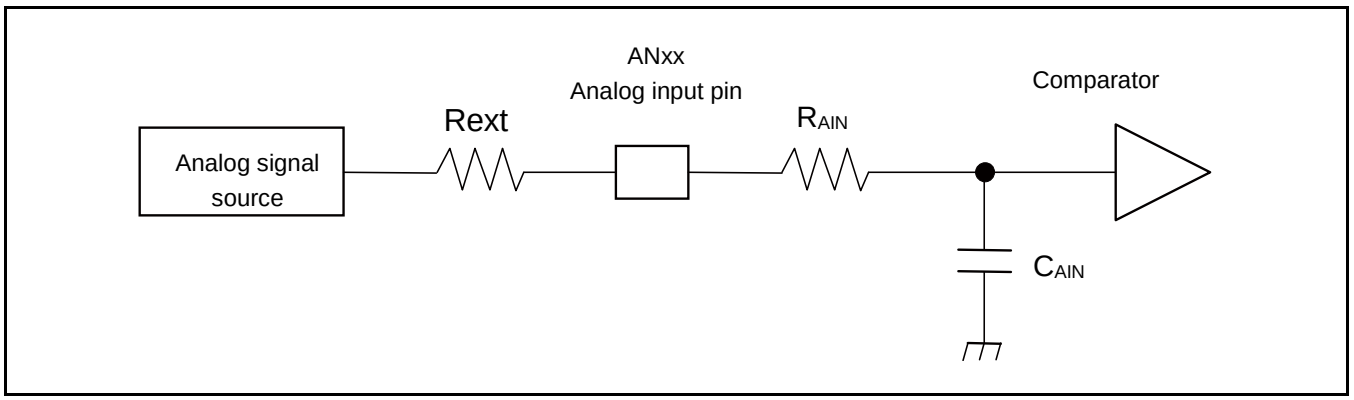
MII Receiving (100 Mbps/10 Mbps)

($ETHV_{CC}$ = 3.0V to 3.6V, 4.5V to 5.5V, V_{SS} = 0V, C_L = 25 pF)

Parameter	Symbol	Pin Name	Conditions	Value		Unit
				Min	Max	
Receiving clock cycle time*	t_{RXCYC}	E_RXCK_REFCK	100 Mbps 40 ns (typical)	-	-	ns
			100 Mbps 400 ns (typical)	-	-	ns
Receiving clock High pulse width duty cycle	t_{RXCYCH}	E_RXCK_REFCK	t_{RXCYCH}/t_{RXCYC}	35	65	%
Receiving clock Low pulse width duty cycle	t_{RXCYCL}	E_RXCK_REFCK	t_{RXCYCL}/t_{RXCYC}	35	65	%
Received data → REFCK ↑Setup time	t_{MIIRXS}	E_RX03, E_RX02, E_RX01, E_RX00, E_RXDV	-	5	-	ns
REFCK ↑ → Received data Hold time	t_{MIIRXH}	E_RX03, E_RX02, E_RX01, E_RX00, E_RXDV	-	2	-	ns

*: The reference clock is fixed to 50 MHz in the RMII specifications.
The clock accuracy should meet the PHY-device specifications.





(Equation 1) $t_S \geq (R_{AIN} + R_{ext}) \times C_{AIN} \times 9$

t_S: Sampling time

R_{AIN}: Input resistance of A/D = 1.2 kΩ at 4.5 V ≤ AV_{CC} ≤ 5.5 V

Input resistance of A/D = 1.8 kΩ at 2.7 V ≤ AV_{CC} < 4.5 V

C_{AIN}: Input capacity of A/D = 12.05 pF at 2.7 V ≤ AV_{CC} ≤ 5.5 V

R_{ext}: Output impedance of external circuit

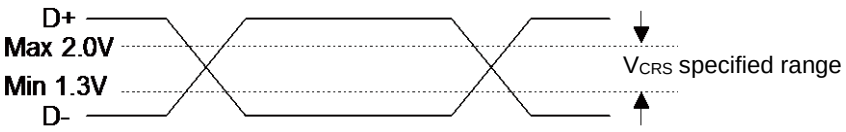
(Equation 2) $t_C = t_{CCK} \times 14$

t_C: Compare time

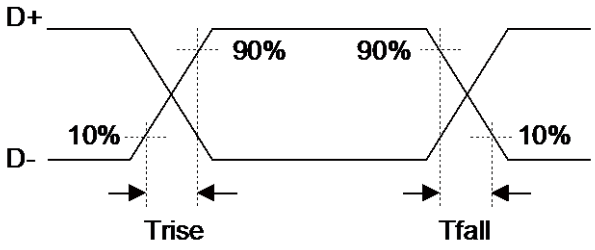
t_{CCK}: Compare clock cycle

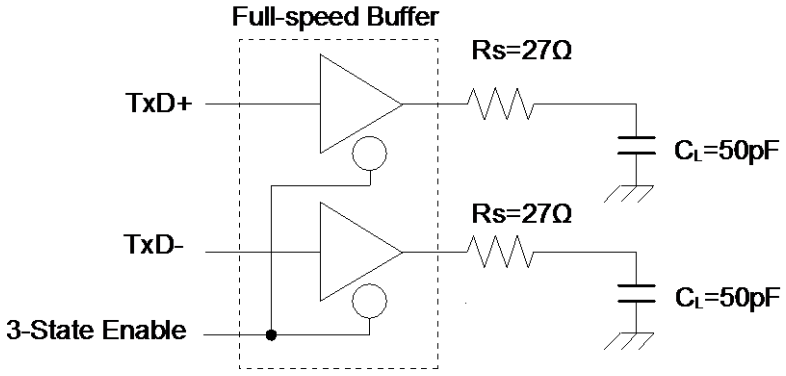
*3: The output drive capability of the driver is below 0.3 V at low state (V_{OL}) (to 3.6 V and 1.5 kΩ load), and 2.8 V or above (to the VSS and 1.5 kΩ load) at high state (V_{OH}).

*4: The cross voltage of the external differential output signal (D +/D −) of USB I/O buffer is within 1.3 V to 2.0 V.



*5: They indicate rise time (T_{RISE}) and fall time (T_{FALL}) of the full-speed differential data signal.
They are defined by the time between 10% and 90% of the output signal voltage.
For full-speed buffer, t_R/t_F ratio is regulated as within ± 10% to minimize RFI emission.





12.11 Standby Recovery Time

12.11.1 Recovery Cause: Interrupt/WKUP

The time from the interrupt occurring to the time of program operation start is shown.

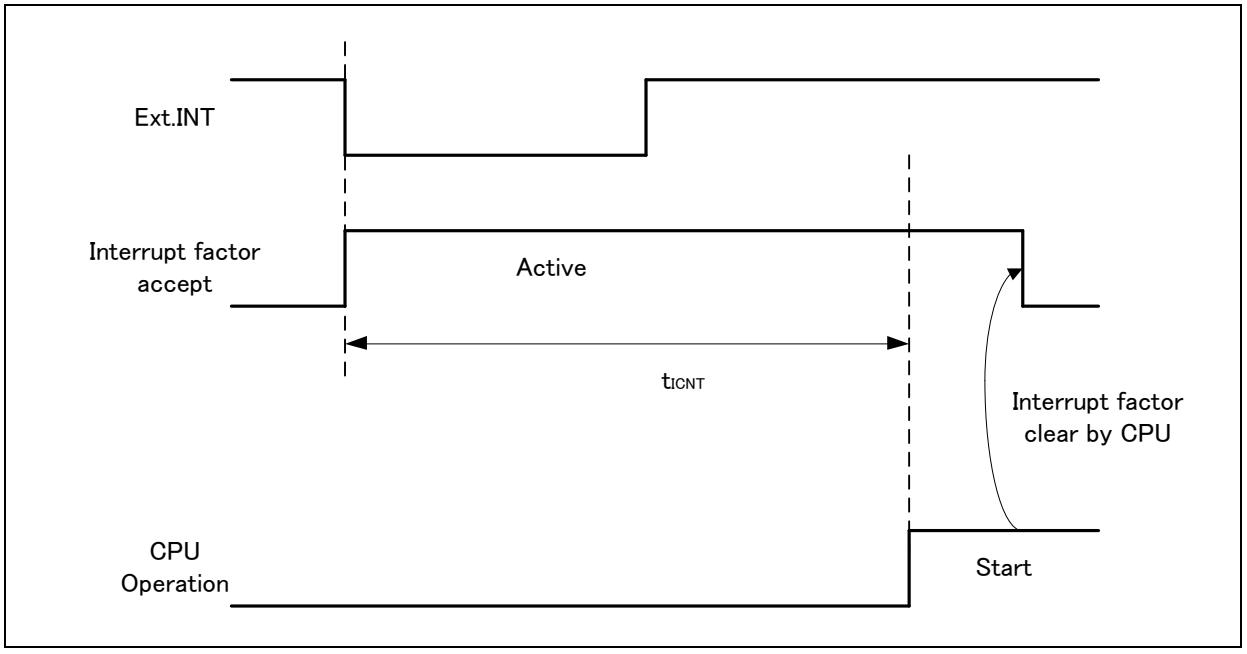
Recovery Count Time

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
Sleep mode	t_{ICNT}	HCLK×1		µs	
High-speed CR Timer mode Main Timer mode PLL Timer mode		40	80	µs	
Low-speed CR Timer mode		450	900	µs	
Sub Timer mode		896	1136	µs	
RTC mode Stop mode (High-speed CR/Main/PLL Run mode return)		316	581	µs	
RTC mode Stop mode (Low-speed CR/sub Run mode return)		270	540	µs	
Deep Standby RTC mode with RAM retention		365	667	µs	without RAM retention
Deep Standby Stop mode with RAM retention		365	667	µs	with RAM retention

*: The maximum value depends on the built-in CR accuracy.

Example of Standby Recovery Operation (when in External Interrupt Recovery*)



*: External interrupt is set to detecting fall edge.

Document History

Document Title: S6E2C2 Series 32-bit ARM® Cortex®-M4F, FM4 Microcontroller
Document Number: 002-05030

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	-	AKIH	04/22/2015	New Spec.
*A	5126421	HITK	02/05/2016	Company name and layout design change. Added the note of TAP pin. Updated Package Code and Dimensions (LQFP-144, LQFP-176, LQFP-216).
*B	5634625	YSKA	02/20/2017	Deleted CAN in communications interfaces. (Page 1) Deleted CAN(RX0_2, TX0_2) in LQQ216 pin assignments (Page 12) Deleted RX2_0 in P7D in “4. Pin Descriptions” (Page 20) Updated 12.4.8 Power-On Reset Timing. Changed parameter from “Power Supply rise time (t_{VCCR})[ms]” to “Power ramp rate(dV/dt)[mV/us]” and add some comments. (Page 117) Modified CSIO timing typo (12.4.12 CSIO(SPI) Timing) Deleted “SPI=1, MS=0” in the titles and added MS=0,1 in the schematic (Page 138-145, 154-161) Modified RTC description (Features, Real-Time Clock (RTC)) Deleted “second, or day of the week” in the Interrupt function. (Page.3) Modifications related to the VBAT in the following chapter. “7. Handling Devices” Notes on Power-on (Page 77) “11. Pin Status in Each CPU State” List of VBAT Domain Pin Status (Page 93) “12.3.1 Current Rating” Table12-9. Typical and Maximum Current Consumption in Deep Standby STOP Mode, Deep Standby RTC Mode and VBAT (Page 109) Deleted MPNs below from “3. Ordering Information” (Page 199) S6E2C28H0AGV20000, S6E2C29H0AGV20000, S6E2C2AH0AGV20000, S6E2C28HHAGV20000, S6E2C29HHAGV20000, S6E2C2AHHAGV20000, S6E2C28J0AGV20000, S6E2C29J0AGV20000, S6E2C2AJ0AGV20000, S6E2C28JHAGV20000, S6E2C29JHAGV20000, S6E2C2AJHAGV20000, S6E2C28J0AGB10000, S6E2C29J0AGB10000, S6E2C2AJ0AGB10000, S6E2C28JHAGB10000, S6E2C29JHAGB10000, S6E2C2AJHAGB10000, S6E2C28L0AGL20000, S6E2C29L0AGL20000, S6E2C2AL0AGL20000, S6E2C28LHAGL20000, S6E2C29LHAGL20000, S6E2C2ALHAGL20000 Added MPNs below to “3. Ordering Information” (Page 199) S6E2C28H0AGV2000A, S6E2C29H0AGV2000A, S6E2C2AH0AGV2000A, S6E2C28HHAGV2000A, S6E2C29HHAGV2000A, S6E2C2AHHAGV2000A, S6E2C28J0AGV2000A, S6E2C29J0AGV2000A, S6E2C2AJ0AGV2000A, S6E2C28JHAGV2000A, S6E2C29JHAGV2000A, S6E2C2AJHAGV2000A, S6E2C28J0AGB1000A, S6E2C29J0AGB1000A, S6E2C2AJ0AGB1000A, S6E2C28JHAGB1000A, S6E2C29JHAGB1000A, S6E2C2AJHAGB1000A, S6E2C28L0AGL2000A, S6E2C29L0AGL2000A, S6E2C2AL0AGL2000A,